

**Product
Bulletin**

E30-100

Thermally conductive epoxy insulator for heat sink applications. Ideal for casting, potting, or as an adhesive for high heat dissipation.

GENERAL DESCRIPTION

E30-100 is designed for the fastest and most continuous high heat transfer. E30-100 measures several time faster heat dissipation than other commercially available types. The most important breakthrough is the handling of E30-100. This system can be easily mixed and poured to form a dimensionally stable heat transfer package.

Mil Spec Thermal Shock Requirements are exceeded by E30-100 while maintaining low expansion.

Outstanding features are the excellent thermal shock and high temperature resistance (class H with Catalyst E30-100B) properties.

E30-100 is ideal for large castings because of its low shrinkage and low exotherm during cure.

Sample kits are available from stock.

SPECIFICATIONS
HANDLING CHARACTERISTICS

Workable Pot Life, 100 g @ 25°C: 1.5 hrs.
Mixed Viscosity @ 25°C cps: 55,000
Color: black

PHYSICAL CHARACTERISTICS

Shrinkage Linear, in / in: 0.003
Hardness, Shore D: 90
Specific Gravity, 25°C / 25°C: 1.90
Tensile Strength, psi: 8,800
Compressive Strength, psi: 15,000

THERMAL CHARACTERISTICS

Thermal Conductivity, btu / hr / ft² / °F / in: 25
Thermal Expansion Coefficient,
(cm / cm / °C · 10⁻⁵): 1.4
Heat Distortion, °C: 105
Operating Temperature Range, °C: -60 to +170

ELECTRICAL CHARACTERISTICS

Dielectric Strength, volts / mil: 485
Dielectric Constant, 60 Hz: 4.4
Dissipation Factor, 60 Hz: 0.015
Volume Resistivity, ohm · cm: 1.5 x 10¹⁵

APPLICATION (Room Temperature Curing)

1. By weight, thoroughly mix 5 parts Catalyst E30-100A to 100 parts resin.
2. Degas and pour; cure at room temperature for 8 hours at 25°C ambient.

APPLICATION (Heat Curing)

1. By weight, thoroughly mix 10 parts Catalyst E30-100B to 100 parts resin.
2. Degas and pour; cure for 2 hours at 100°C.